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SPECIFCATION

产品名称: LAMP	客户:				
产品型号: B503IR4CCP14-940	机型:				
规格描述: 5mm 发射管-940	日 期: 2016年9月28日				
设 计:	日期:				
审 核:					
批 准:	承 办:				
客户确认					
签 名:	日期:				
结论:					

客户资

料

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DOSMF CHIEF LANJIN ELECTRONICS CO.,LTD.

Technical Data Sheet (Preliminary)

Features

High reliability

p = 940

- High radiant intensity
- Peak wavelength 940nm
- Pb free.
- •The product itself will remain within RoHs compliant version

Descriptions

• Due to the package design, the LED has wideviewing angle and optimized light coupling by inter reflector. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

Applications

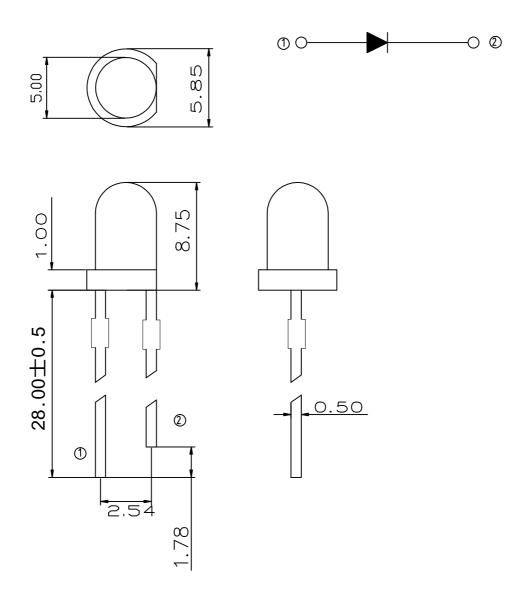
- Telecommunication, indicator and backlighting in telephone and fax.
- Flat backlight for LCD's, switches and symbols.
- Light pipe application.
- •General use.

Device Selection Guide

	Lens Color			
Type	Material	Emitted Color	Lens Color	
B503IR4CCP14-940	GaAlAs	IR	Water Clear	

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Package Outline Dimensions



Note:The tolerances unless mentioned is±0.1mm;Unit=mm

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Absolute Maximum Ratings(ta=25°C)

ITEMS	SYMBOL		UNIT			
Reverse Voltage	VR		V			
Forward Current	If	IR	100	MA		
Operation Temperature	Topt		°C			
Storage Temperature	Tstg		°C			
Electrostatic Discharge(HBM)	ESD	IR 2000		V		
Power Dissipation	Pt	IR 150		MW		
Peak Forward Current(Duty 1/10 @1KHZ	IFP	IR 1000		mA		
Soldering Temperature	Tsol	Reflow Soldering :260°C for 10 sec Hand Soldering :300°C for 3 sec				

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BOSM CHIEF LANJIN ELECTRONICS CO.,LTD.

Technical Data Sheet (Preliminary)

■ Absolute Maximum Ratings(ta=25°C)

Parameter	Symbol		Min.	Тур.	Max.	Unit	Condition
Rediant Intensity	Ee	IR	7.8		17.6	mW/SR	IF=20 mA
Peak Wavelength	λP	IR	-	940		nm	IF=20 mA
Dominant Wavelength	λd	IR			_	nm	IF=20 mA
Spectrum Radiation Bandwidth	Δλ	IR	_	45	_	nm	IF=20 mA
Forward Voltage	Vf	IR	1.3	1.45	1.6	v	IF=20 mA
Viewing Angle	201/2			30		deg	IF=20 mA
Reverse Current	Ir	IR			10	uA	VR=5v

^{*}For each die

Notes:

1. Tolerance of Luminous Intensity $\pm 3\%$

2. Tolerance of Dominant Wavelength

±1nm

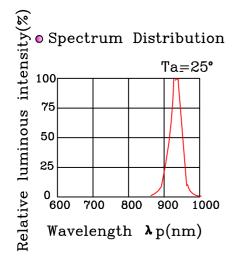
3.Tolerance of Forward Voltage ±0.03V

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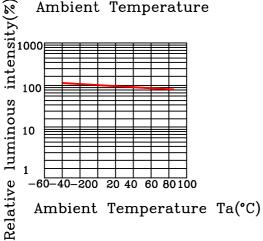
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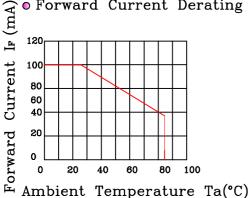
Typical Electrical-Optical Characteristics Curves(IR)



Luminous Intensity Vs. Ambient Temperature



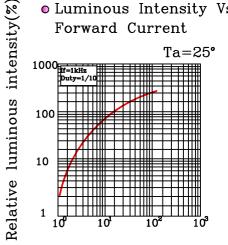
• Forward Current Derating Curve



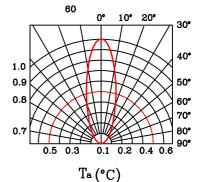
Forward Current Vs Forward Current ${
m Ir}({
m mA})$ Forward Vottage Ta=25° 1000 100 10

Forward Voltage(V_F)-volts

• Luminous Intensity Vs. Forward Current



Forward Current If (mA) Radiation Diagram



Forward Current Ir(mA)

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Technical Data Sheet (Preliminary)

The reliability of products shall be satisfied with items listed below. Confidence level: 90%

LTPD:10%

NO	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp: 260±5°C	6min	22 PCS	0/1
2	Temperature Cycle	H:+100°C15min f 5min L:-40°C15min	300 Cycles	22 PCS	0/1
3	Thermal Shock	H:+100°C 5min \$\int 10\sec L:-10°C 5min	300 Cycles	22 PCS	0/1
4	High Temerature Storage	Temp :100°C	1000 Hrs	22 PCS	0/1
5	LowTemperature Storage	Temp :-40°C	1000 Hrs	22 PCS	0/1
6	DC Operating Life	IF=20mA	1000 Hrs	22 PCS	0/1
7	High Temperature High Humidity	85°C/85%RH	1000 Hrs	22 PCS	0/1

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Technical Data Sheet (Preliminary)

■Guideline for Soldering(1)

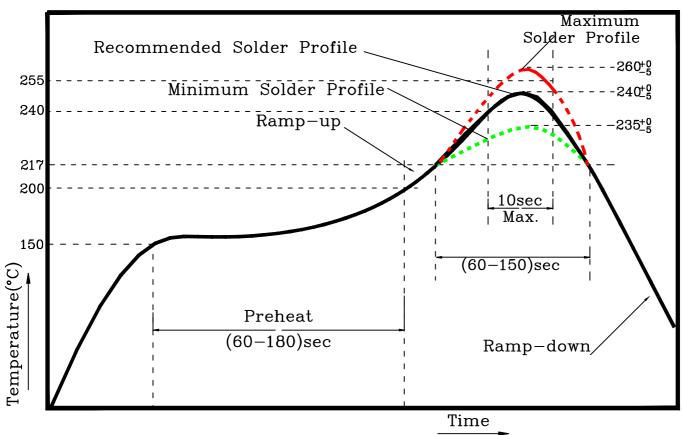
Hand Soldering

A soldering iron of less than 20W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300°C while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

Be careful because the damage of teh product is often started at teh time of the hand soldering.

• Reflow Soldering

Use the conditions shown in the under Figure of Pb-Free Reflow Soldering.



- Reflow soldering should not be done more than two times .
- Stress on the LEDs should be avoided during heating in soldering process
- Afer soldering, do not deal with the product before its temperature drop down to room temperature.

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DOSMF CHIEF LANJIN ELECTRONICS CO.,LTD.

Technical Data Sheet (Preliminary)

■Precautions(1)

Storage

Moisture proof and anti- electrostatic package with moisture absorbent material is used , to keep moisture to a minimum $\,$

Before opening the package, the product should be kept at 30°C or less and humidity less than 60%Rh, and be used within a year.

Afer opening the package, the product should be stoted at 30or less and humidity less than 10%RH, and be soldered within 24 hours. It is recommended that the product be operated at the workshop condition of 30°C or less and humidity less than 60%RH

If the moisture absorbent material has fade away or the LEDS have exceeded the storage time, baking treatment. should be performed based on the following condition: (60+5C) for 12 hours.

• Static Electricity

Static electricity or surge voltage damages the LEDs . Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current . even not light

All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

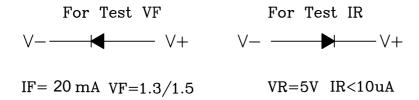
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Precautions(2)

• Design Consideration

In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen.

It is recommended to use Circuit Awhich regulates the current flowing through each LED rather than Circuit B. in forward V oltage (Vf) of the LEDs.In the worst case ,some LED may be subjected to stresses in excess of the Absolute Maximum Rating



• Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Colr changed and so on.Please consider the htat generation of the LEDs when making the system design.

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